

Wide bandwidth JFET Input Operational Amplifier in bare die form

Rev 1.0 23/06/18

Description

The SiS1057 JFET input amplifier combines precision specifications with high speed performance. A slew rate of $50V/\mu s$ with $1.5~\mu s$ settling time to 0.01% is suited for high speed sample + hold circuits and data converters. Low bias current and offset characteristics benefit applications requiring greater precision at speed, such as peak detectors, photodiode amplifiers and log amplifiers. The device exhibits low voltage and current noise at either high or low source impedance. Low drift over temperature delivers improved stability. This device is characterised over the full military temperature range.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-883 /2010B Visual Inspection
- "H" MIL-STD-883 /2010B Visual Inspection+ MIL-PRF-38534 Class H LAT
- "K" MIL-STD-883 /2010A Visual Inspection (Space)
 + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

Features:

Wide gain bandwidth: 20MHz ($A_V = 5$)

High speed: 50V/μs slew rate, 1.5 μs settling time

■ Low noise: 12nv/√Hz (10KHz)

Low input bias current: 30pA

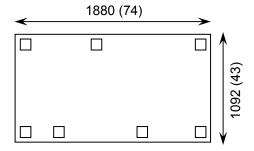
■ Low drift input offset voltage: 1mV, 3µV/°C

Common-Mode Rejection: 100 dB

Open-Loop gain: 106 dB

Differential input voltage range ≤ supply voltage

Die Dimensions in µm (mils)



Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 460µm(18 Mils) On request
- Assembled into Ceramic Package On request

Mechanical Specification

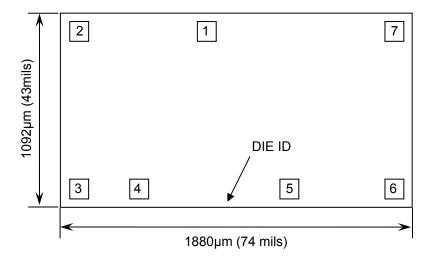
Die Size	1880 x 1092 74 x 43	µm mils	
Minimum Bond Pad Size	100 x 100 4 x 4	μm mils	
Die Thickness	460 (±20) 18 (±0.79)	μm mils	
Top Metal Composition	Al 1%Si 1.1µm		
Back Metal Composition	N/A – Bare Si		





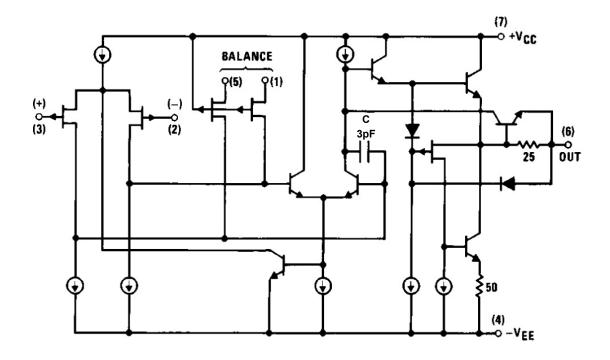
Rev 1.0 23/06/18

Pad Layout and Functions



PAD	FUNCTION					
1	BALANCE					
2	IN-					
3	IN+					
4	V-					
5	BALANCE					
6	OUTPUT					
7	V+					
СО	CONNECT CHIP BACK TO V-					

Simplified Schematic







Rev 1.0 23/06/18

Absolute Maximum Ratings¹

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_S	±22	V
Input Differential Voltage Range	V_{IDR}	±40	V
Input Voltage Range ²	V_{l}	±20	V
Output Short Circuit to Ground	-	Continuous	-
Electrostatic Discharge ³	V_{ESD}	±1000	V
Power Dissipation in Still Air	P_{D}	570	mW
Storage Temperature	T_{STG}	-65 to +150	°C
Junction Temperature	TJ	150	°C

- 1. Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability.
- 2. Unless otherwise specified the absolute maximum negative input voltage is equal to the negative power supply voltage.
- 3. 100 pF discharged through 1.5-k Ω resistor, Human body model (HBM).

Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNITS
DC Supply Voltage	V _{CC}	±15	±20	V
Operating Temperature	TJ	-55	+125	°C

DC Electrical Characteristics (-55°C ≤ T_J ≤ +125°C, ±15V ≤ V_S ≤ ±20V unless otherwise specified)

PARAMETER	SYMBOL	MBOL CONDITIONS		LIMITS			UNITS
FARAIVIETER	STWIBOL			MIN	TYP	MAX	
Institute Official Vallages	$R_S = 50\Omega$,	25°C	-	1	2	mV	
Input Offset Voltage	V _{IO}	$V_{CM} = 0V$	125°C	-	-	2.5	IIIV
Input Offset Voltage Drift	ΔV _{IO} /ΔΤ	$R_S = 50\Omega$, $V_{CM} = 0V$		-	3	5	μV/°C
Change in Drift with V _{OS} adjust ⁴	ΔTC / V _{IO}			-	0.5	-	μV/°C per mV
Input Offset Current	I _{IO} V _{CM} = 0V	V - 0V	25°C	-	3	10	pA
		V _{CM} = UV	125°C	-	-	10	nA
Input Bias Current ⁵	1	\/ - 0\/	25°C	-	30	50	рА
input Bias Current	I_{IB} $V_{CM} = 0V$	V _{CM} – UV	125°C	-	-	25	nA
Supply Current	I _{cc}	V _s = ±15V 25°C		-	5	6	mA
Common Mode Input Voltage range	V _{ICR}	V _s = ±15V		±11	+15.1 -12	-	V

- **4.** Temperature Coefficient of the adjusted input offset voltage changes 0.5mV/°C typically for each mV of adjustment from it's original unadjusted value. Common-mode rejection and open loop voltage gain are unaffected by offset adjustment.
- 5. In normal operation junction temperature rises above ambient temperature as a result of internal power dissipation, Pd. $T_J = T_A + \theta_J A$, where $\theta_J A$ is the thermal resistance from junction to ambient. Use of a heat sink is recommended to minimalize input bias current.





Rev 1.0 23/06/18

DC Electrical Characteristics (-55°C ≤ T_J ≤ +125°C, ±15V ≤ V_S ≤ ±20V unless otherwise specified)

		SYMBOL CONDITIONS		LIMITS			· · · · ·
PARAMETER	SYMBOL			MIN	TYP	MAX	UNITS
Input Resistance	R _{IN}	T _J = 25°C		-	10 ¹²	-	Ω
Large-Signal Open- Loop Voltage Gain	A_{VOL} $V_O = \pm 10^{\circ}$	$V_S = \pm 15V$,	25°C	50	200	-	- V/mV
		$R_L \ge 2K\Omega$	125°C	50	-	-	V/IIIV
Output Voltage Swing	V	$V_{O} = \frac{V_{S} = \pm 15V, R_{L} = 10K\Omega}{V_{S} = \pm 15V, R_{L} = 2K\Omega}$		±12	±13	-	V
	v _o			±10	±12	-	
Common-Mode Rejection Ratio	CMRR			85	100	-	dB
Power Supply Rejection Ratio	PSSR			85	100	-	dB

AC Electrical Characteristics (T_J = 25°C, V_S = ±15V unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS			LIMITS		UNITS	
PARAMETER	STWIBOL			MIN	TYP	MAX	UNITS	
Slew Rate	SR	A _V = 5		40	50	-	V/µs	
Gain Bandwidth	GBW			15	20	-	MHz	
Settling Time	ts	A _V = -5, 10V Step 0.01%		-	1.5	-	μS	
Equivalent Input		R _S = 100Ω	R _S = 100Ω	f _O = 100Hz	-	15	-	nV/√Hz
Noise Voltage	e _n			1\(\s\) = 100\(\sum_2\)	f _O = 1KHz	-	12	-
Equivalent Input		R _S = 100Ω	f _O = 100Hz	-	0.01	-	pA/√Hz	
Noise Current	I _n		f _O = 1KHz	-	0.01		PAV VIIZ	
Input Capacitance	C _{IN}			-	3	-	pF	

Typical DC Characteristics

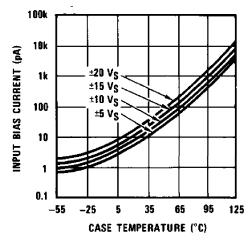


FIGURE 1. Input Bias Current

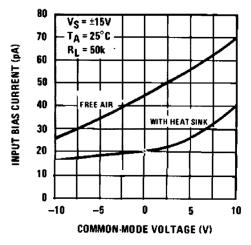


FIGURE 2. Input Bias Current V_{CM}





Rev 1.0 23/06/18

Typical DC Characteristics continued

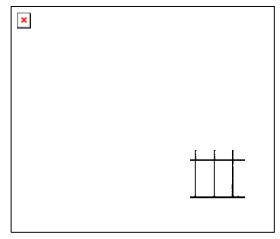


FIGURE 3. Supply Current

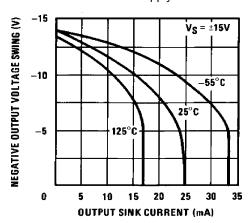


FIGURE 5. Negative Current Limit

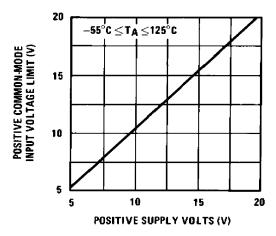


FIGURE 7. Positive Common-Mode Input Voltage Limit

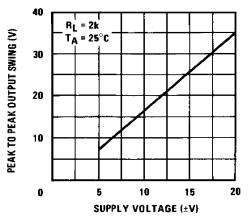


FIGURE 4. Voltage Swing

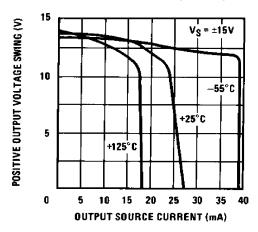


FIGURE 6. Positive Current Limit

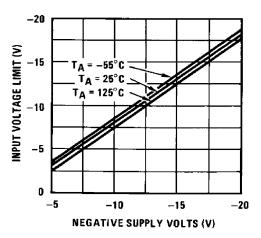


FIGURE 8. Negative Common-Mode Input Voltage Limit





Rev 1.0 23/06/18

Typical DC Characteristics continued

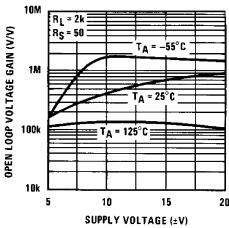


FIGURE 9. Open-Loop Voltage Gain

PEAK TO PEAK OUTPUT SWING (V) 24 20 16 12 10 OUTPUT LOAD R_L ($k\Omega$)

FIGURE 10. Output Voltage Swing

Typical AC Characteristics

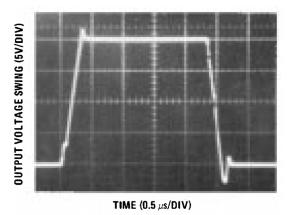
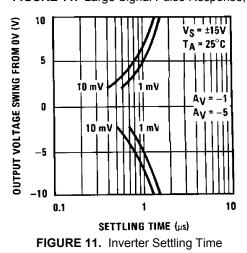
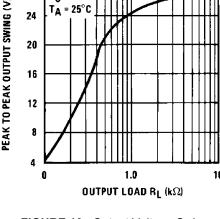


FIGURE 11. Large Signal Pulse Response, A_V = +5





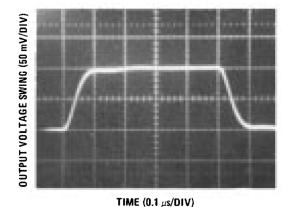


FIGURE 12. Small Signal Pulse Response, $A_V = +5$

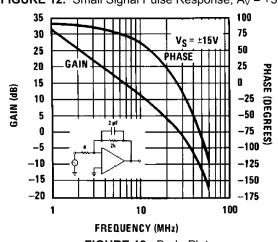


FIGURE 12. Bode Plot





Rev 1.0 23/06/18

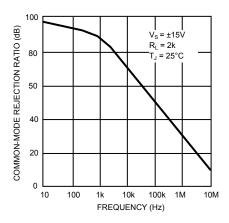


FIGURE 13. COMMON-MODE REJECTION RATIO

DISCLAIMER: The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Silicon Supplies Ltd hereby disclaims any and all warranties and liabilities of any kind.

LIFE SUPPORT POLICY: Silicon Supplies Ltd components may be used in life support devices or systems only with the express written approval of Silicon Supplies Ltd, if a failure of such components can reasonably be expected to cause the failure of that life support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

